

MULTILAYER CIRCUIT COMPONENT AND
METHOD FOR MANUFACTURING THE SAME

ABSTRACT OF THE DISCLOSURE

A multilayer circuit component and a method for manufacturing the same, in which the difference of the amounts of baking shrinkages between each of the glass-containing layers is small, and the enlargement rate of the diameter of the via hole formed in each of the glass-containing layers is close to those in the other layers, so that it is possible to prevent a short circuit defect due to the mutual short circuit of the conductors in the via hole from occurring, and the warp of the substrate is reduced. The multilayer circuit component is provided with at least two glass-containing layers on a substrate, differentiating the softening temperature of glass compounded in the first glass-containing layer formed on the substrate from the softening temperature of glass compounded in the second glass-containing layer formed on the first glass-containing layer. The difference in the sintering properties due to the difference between the wettabilities is counterbalanced, and therefore, a multilayer circuit component, in which the warp of the substrate is reduced, and the degree of the enlargement of the via hole diameter of each of the glass-containing layers during baking is uniform, is produced.

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